Temperature Compensated Crystal Oscillator (TCXO)

· Package size (2.5 mm \times 2.0 mm \times 0.8 mm)

High stability TCXO

· Output waveform : Clipped sine wave

[1] Product Number / Product Name

(1-1) Product Number / Ordering Code

X1G0054210313xx

last 2 digits code(xx) define Quantity. The standard is "27", 10 000 pcs/Reel.

(1-2) Product Name / Model Name

TG2520SMN 25.000000 MHz MCGNNM

[2] Operating Conditions

Parameter	Symbol	:	Specification	S	Unit	Conditions
Faiaillelei	Symbol	Min.	Тур.	Max.	Onit	Conditions
Supply voltage	Vcc	2.66	-	3.465	V	-
Supply voltage	GND	0	-	0	V	-
Operating temperature range	T_use	-40	-	+85	°C	-
	Load_R	9	10	11	kΩ	-
Output load	Load_C	9	10	11	pF	-
	Cc	0.01	-	-	μF	DC-cut capacitor *

* DC-cut capacitor is not included in this TCXO. Please attach an external DC-cut capacitor to the out pin.

[3] Frequency Characteri	(Vcc =	2.66 to 3.465	5 V, GND = 0.0) V, Load = 1	0 kΩ // 10 pF, T_use = +25 °C)	
Parameter	Symbol		Specification	S	Unit	Conditions
Falameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Output Frequency	fo	-	25	-	MHz	
Frequency tolerance	f_tol	-0.5	-	+0.5	x10⁻⁵	T_use = +25 °C ± 2 °C Before reflow
Frequency tolerance *1	f_tol	-1.5	-	+1.5	x10 ⁻⁶	T_use = +25 °C ± 2 °C After 2 reflows *2
Frequency / temperature characteristics	fo-Tc	-0.5	-	+0.5	x10⁻⁵	T_use = -40 °C to +85 °C (Reference to +25 °C)
Frequency / load coefficient	fo-Load	-0.1	-	+0.1	x10 ⁻⁶	Load ± 10 %
Frequency / voltage coefficient	fo-Vcc	-0.1	-	+0.1	x10 ⁻⁶	Vcc ± 5 % *3
Frequency aging *4	f age	-0.5	-	+0.5	x10 ⁻⁶	T_use = +25 °C first year
Frequency aging *4	f_age	-3.5	-	+3.5	x10 ⁻⁶	T_use = +25 °C 10 years

*1 Include initial frequency tolerance and frequency deviation after reflow cycles.

*2 Measured in the elapse of 24 hours after reflow soldering.

*3 Vcc ± 5 % must be in operating supply voltage range (2.66 V to 3.465 V)

*4 Aging stability is estimated from environmental reliability tests; expected amount of the frequency variation.

[4] Electrical Characteristics (Vcc = 2.66 to 3.465 V, GND = 0.0 V, Load = $10 \text{ k}\Omega // 10 \text{ pF}$, T_use = +25 °C)

Parameter	Symbol	Symbol Specifications			Unit	Conditions
Falameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Current consumption	lcc	-	-	1.5	mA	-
Output level	Vpp	0.8	-	-	V	Peak to peak voltage
Symmetry	SYM	45	50	55	%	GND level (DC-cut)
Start up time	t str	-	-	2.0	ms	Until frequency has been reached within $\pm 0.5 \times 10^{-6}$ of final freq.
	1_011	-	-	1.0	ms	Until output signal has been reached min 90 % of final amp.
Harmonics	-	-	-	-5.0	dBc	3rd harmonics

High stability and Low phase noise temperature compensated crystal oscillator (TCXO) Product name : TG2016SMN / TG2520SMN

: -40 °C to +85 °C

: -161 dBc/Hz

Features

- High stability
- Frequency range
 - : 10 MHz to 55 MHz
- Output : Clipped Sine
- Supply voltage : 1.7 V to 3.63 V
- Frequency / temperature characteristic : ±0.5 x10⁻⁶ Max.
- Operating temperature
- Phase Noise

(fo = 26 MHz, 100 kHz offset)

Applications

- GNSS
- RF
- Wireless communication devices
- LTE, WIMAX, WI-FI, W-LAN
- IoT etc..

Outline dimensions



Pin information

Pin #	Connection
1	N.C. (TCXO)
1	Vc (VC-TCXO)
2	GND
3	OUT
4	V _{cc}

Characteristics Frequency / temperature characteristics fo = 26 MHz, n = 40 pcs



Frequency slope

 R_{OH}

TG2016SMN

and MHz fundamental crystal.

Description

(2.0 imes 1.6 imes 0.73 mm)

and other wireless communication devices.

Compliant

TG2520SMN

TG2016SMN / TG2520SMN are high stability and low phase

noise TCXOs using an Epson-developed and fabricated IC

The phase noise is the lowest of Epson's compact TCXO products lineup, making it an ideal reference clock for GNSS

 $(2.5 \times 2.0 \times 0.8 \text{ mm})$

fo = 26 MHz, n = 40 pcs



[1] Product Number / Product Name

(1) Product Name (Standard Form)

<u>TG20</u>	<u>16 S MN</u>	<u>26.000000MHz</u>	E	<u>C</u>	G	N	N	M
1	$\overline{2}$	3	4	5	6	\bigcirc	8	9

①Model (TG2016, TG2520) ②Output (S: Clipped sine) ③Frequency ④Supply voltage (Refer to symbol table)

(5) Frequency / temperature characteristics (C: $\pm 0.5 \times 10^{-6}$ Max., F: $\pm 2.0 \times 10^{-6}$ Max.) (6) Operating temperature (G: -40 °C to +85 °C) (7) Standby function (N: Non) (8) V_C function(Refer to symbol table, N: Non for TCXO) (9) Internal identification code ("M" is default)

④Supply voltage[Vcc], ⑧Vc function[Vc] (Symbol table)									
Voltage [V]	тсхо		VC-	тсхо					
④Vcc	E:1.8	E:1.8	B:2.8	A:3.0	C:3.3				
(Typ.)	M:2.8 to 3.3								
⑧Vc (Typ.)	N: Non	B 0.9	C:1.4	D 1.5	E 1.65				

(2) Product Number / Ordering Code

Please refer to the web site for the latest information

Frequency	Part number				
[MHz]	TG2520SMN (Size: 2.5 x 2	.0)	TG2016SMN (Size: 2.0 x 1.6)		
	±0.5 ppm (-40 to +85 °C),	without VC function	±0.5 ppm (-40 to +85 °C), v	without VC function	
	V _{CC} = 1.8 V	V _{CC} = 2.66 to 3.465 V	V _{CC} = 1.8 V	V_{CC} = 2.66 to 3.465 V	
	Suffix: ECGNNM	Suffix: MCGNNM	Suffix: ECGNNM	Suffix: MCGNNM	
16	X1G005421020827	X1G005421030827	X1G005441020825	X1G005441030825	
16.368	X1G005421020127	X1G005421030127	X1G005441020125	X1G005441030125	
16.369	X1G005421020227	X1G005421030227	X1G005441020225	X1G005441030225	
19.2	X1G005421020327	X1G005421030327	X1G005441020325	X1G005441030325	
20	X1G005421021127	X1G005421031127	X1G005441021125	X1G005441031125	
24	X1G005421021227	X1G005421031227	X1G005441021225	X1G005441031225	
25	X1G005421021327	X1G005421031327	X1G005441021325	X1G005441031325	
26	X1G005421020427	X1G005421030427	X1G005441020425	X1G005441030425	
27	X1G005421021427	X1G005421031427	X1G005441021425	X1G005441031425	
27.6	X1G005421022127	X1G005421032127	X1G005441022125	X1G005441032125	
30	X1G005421021527	X1G005421031527	X1G005441021525	X1G005441031525	
32	X1G005421020527	X1G005421030527	X1G005441020525	X1G005441030525	
38.4	X1G005421020627	X1G005421030627	X1G005441020625	X1G005441030625	
40	X1G005421020727	X1G005421030727	X1G005441020725	X1G005441030725	
48	X1G005421021627	X1G005421031627	X1G005441021625	X1G005441031625	
50	X1G005421022227	X1G005421032227	X1G005441022225	X1G005441032225	
52	X1G005421022027	X1G005421032027	X1G005441022025	X1G005441032025	

[2] Absolute maximum ratings

Parameter	Symbol	Symbol		Unit	Conditions		
Farameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Supply voltage	V_{CC} -GND	-0.5	-	+4.0	V		
Frequency control voltage	Vc-GND	-0.5	-	V _{CC} + 0.5	V	Vc Terminal	
Storage temperature range	T_stg	-40	-	+90	- (,	Storage as single product	

[3] Recommended operating conditions

Parameter	Symbol	Symbol Specifications			Unit	Conditions
i alametei	Symbol	Min.	Тур.	Max.	Offic	Conditions
		1.7	1.8	1.9	V	$V_{CC} = 1.8 \text{ V} \pm 0.1 \text{ V}$
Supply voltage	V _{cc}	-5 %	2.8	+5 %	V	$V_{CC} = 2.8 V \pm 5 \%$
Supply voltage	v cc	-5 %	3.0	+5 %	V	$V_{CC} = 3.0 V \pm 5 \%$
		-5 %	3.3	+5 %	V	$V_{CC} = 3.3 V \pm 5 \%$
Supply voltage	GND	0	-	0	V	
		GND	N.C	—	V	Vc Terminal / TCXO
		0.3	0.9	1.5	V	$Vc = 0.9 V \pm 0.6 V$
Frequency control voltage	Vc	0.4	1.4	2.4	V	Vc = 1.4 V ± 1.0 V
		0.5	1.5	2.5	V	Vc = 1.5 V ± 1.0 V
		0.65	1.65	2.65	V	Vc = 1.65 V ± 1.0 V
Operating temperature range	T_use	-40	+25	+85	°C	
	Load_R	9	10	11	kΩ	
Output load	Load_C	9	10	11	pF	
	Cc	0.01	-	-	μF	DC-cut capacitor *

* DC-cut capacitor is not included in this TCXO. Please attach an external DC-cut capacitor to the out pin.

[4] Frequency characteristics

(4-1) Frequency characteristics

(V_{CC} = Typ., Vc = Typ., Output Load = 10 k Ω // 10 pF, T_use = +25 °C)

Parameter	Parameter Symbol Specifications		6	Unit	Conditions		
T arameter	Symbol	Min.	Тур.	Max.	Offic	Conditions	
		10	-	55			
Output Frequency	fo		16.369, 19.2, 20 0, 32, 38.4, 40,		MHz	Standard Frequency	
Frequency tolerance(before reflow)	f_tol	-0.5	-	+0.5	x10 ⁻⁶	T_use = +25 °C ± 2 °C Before reflow	
Frequency tolerance(after reflow) *	f_tol	-1.5	-	+1.5	x10 ⁻⁶	T_use = +25 °C ± 2 °C After reflow *	
Frequency / temperature characteristics	fo-Tc	-0.5	-	+0.5	x10 ⁻⁶	T_use = -40 °C to +85 °C (Reference to +25 °C)	
Frequency / load coefficient	fo-Load	-0.1	-	+0.1	x10 ⁻⁶	Load ± 10 %	
Frequency / voltage coefficient	fo-V _{CC}	-0.1	-	+0.1	x10 ⁻⁶	V _{CC} ± 5 % **	
Frequency aging_1year ***	f_age_1y	-0.5	-	+0.5	x10 ⁻⁶		
Frequency aging_3year	f_age_3y	-1.5	-	+1.5	x10 ⁻⁶	10 MHz, 12 MHz < fo < 20 MHz,	
Frequency aging_5year	f_age_5y	-2.0	-	+2.0	x10 ⁻⁶	24 MHz \leq fo \leq 40 MHz, 24 MHz \leq fo \leq 40 MHz,	
Frequency aging_10year	f_age_10y	-3.5	-	+3.5	x10 ⁻⁶		
Frequency aging_1year ***	f_age_1y	-1.5	-	+1.5	x10 ⁻⁶		
Frequency aging_3year	f_age_3y	-2.5	-	+2.5	x10 ⁻⁶	10 MHz < fo < 12 MHz, 20 MHz < fo < 24 MHz, 40 MHz < fo <u><</u> 55 MHz	
Frequency aging_5year	f_age_5y	-3	-	+3	x10 ⁻⁶		
Frequency aging_10year	f_age_10y	-5	-	+5	x10 ⁻⁶		

* Measured in the elapse of 2 hours after reflow soldering.

** V_{CC} ± 5 % must be in operating supply voltage range (1.7 V to 3.63 V)

*** Aging stability is estimated from environmental reliability tests; expected amount of the frequency variation.

This does not intend to guarantee the product-life cycle

SEIKO EPSON CORPORATION

1 MHz offset

Parameter	Symbol	Specifications			Unit	Conditions
i alametei	Symbol	Min.	Typ.	Max.	Unit	Conditions
Frequency control range	f.cont	-	-	-5.0	x10 ⁻⁶	$\label{eq:Vc} \begin{array}{c} Vc = 0.9 \ V - 0.6 \ V at \ V_{CC} = 1.8 \ V \\ Vc = 1.4 \ V - 1.0 \ V at \ V_{CC} = 2.8 \ V \\ Vc = 1.5 \ V - 1.0 \ V at \ V_{CC} = 3.0 \ V \\ Vc = 1.65 \ V - 1.0 \ V at \ V_{CC} = 3.3 \ V \end{array}$
requency control range	f_cont -	+5.0	-	-	x10 ⁻⁶	$\label{eq:VC} \begin{array}{l} Vc = 0.9 \; V + 0.6 \; V \; at \; V_{CC} = 1.8 \; V \\ Vc = 1.4 \; V + 1.0 \; V \; at \; V_{CC} = 2.8 \; V \\ Vc = 1.5 \; V + 1.0 \; V \; at \; V_{CC} = 3.0 \; V \\ Vc = 1.65 \; V + 1.0 \; V \; at \; V_{CC} = 3.3 \; V \end{array}$
nput impedance	Zin	500	-	-	kΩ	Vc-GND (DC)
Frequency change polarity	-	F	Positive polar	ity	-	
5] Electrical characterist	ics		(Ver	= Typ Vc = Ty	/p_Output Load =	10 kΩ // 10 pF, T_use = +25 °C
			Specification	<u>s ijp., to ij</u>		
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
		-	-	1.5	mA	10 MHz <u><</u> fo <u><</u> 26 MHz
		-	-	1.8	mA	26 MHz < fo <u><</u> 40 MHz
Current consumption	I _{CC}	-	-	2.0	mA	40 MHz < fo <u><</u> 50 MHz
		-	-	2.1	mA	50 MHz < fo <u><</u> 55 MHz
Output voltage	Vpp	0.8	-	-	Vpp	Peak to peak voltage
Start-up time	t_str	-	-	1.0	ms	Until output signal has been reached min 90% of final amp.
Start-up time	t_str	-	-	2.0	ms	Until frequency has been reached within $\pm 0.5 \times 10^{-6}$ of final frequency.
		-	-	0.050		from 0.1 s to 0.6 s
Frequency drift rate	fo-dfift	-	-	0.014	x10 ⁻⁶	from 0.6 s to 1.6 s
		-	-	0.005		from 1.6 s and up to 40 s
Symmetry	SYM	40	50	60	%	GND level (DC-cut)
Harmonics	Hm	-	-	-10.0	dBc	
		-	-66	-		1 Hz offset
		-	-94	-		10 Hz offset
		-	-120	-		100 Hz offset
Phase noise fo = 26 MHz *	L(f)	-	-142	-	dBc/Hz	1 kHz offset
			174			
	-(1)	-	-157	-	420,112	10 kHz offset

-163

* For other frequencies, refer to Charts (6-8), Phase Noise

[6] Characteristic Data (6-1) "Frequency / temperature characteristics" & "Frequency slope" 16.368 MHz (n = 40 pcs)













26 MHz (n = 40 pcs)











-0.5 -1 -40 -30 -20 -10 0 10 20 30 40 50 60 70 80 90 temp [°C]

48 MHz (n = 40 pcs)

32 MHz (n = 40 pcs)



52 MHz (n = 40 pcs)













(6-2) "Frequency / load coefficient" & "Frequency / voltage coefficient"





(6-5) Frequency control range (26 MHz, T_use = 25 °C, VC-TCXO only)











Input capacitance Max. 10 pF

Band width Min. 300 MHz

Impossible to measure both frequency and wave form at the same time.

(In case of using oscilloscope's amplifier output, possible to measure both at the same time.)

- (2) Load_C includes probe capacitance.
- (3) A capacitor (By-pass: 0.01 μ F to 0.1 μ F) is placed between V_{CC} and GND,and closely to TCXO.
- (4) Use the current meter whose internal impedance value is small.
- (5) Power Supply Impedance of power supply should be as low as possible.

unit : mm

[8] Outline Drawing / Recommended Foot Print (1)TG2016SMN



Terminal coating : Au plating

(2)TG2520SMN



Terminal coating : Au plating



Connection
N.C. (TCXO)
Vc (VC-TCXO)
GND
OUT
V _{CC}

Please keep "N.C." pin OPEN condition or GND connection.

"N.C." pin doesn't work as a ground pin.

For stable operation, please add a bypass capacitor(0.01 μ F to 0.1 μ F) between Vcc and GND. Please place it as close to TCXO as possible.

Please do not place any pattern between footprint pads.



Please keep "N.C." pin OPEN condition or GND connection.

"N.C." pin doesn't work as a ground pin.

For stable operation, please add a bypass capacitor(0.01 μF to 0.1 $\mu F)$ between Vcc and GND. Please place it as close to TCXO as possible.

Please do not place any pattern between footprint pads.

[9] Marking

TG2016SMN / TG2520SMN common



[10] Moisture Sensitivity Level, Electro-Static Discharge

(10-1) Moisture Sensitivity Level (MSL)

Parameter	Specifications	Conditions
MSL	LEVEL1	JEDEC J-STD-020D
(10-2) Electro-Static Discharge (ESD)		
Parameter	Specifications	Conditions
Human Body Model (HBM)	2 000 V Min.	EIAJ ED-4701-1 C111A, 100 pF, 1.5 kΩ, 3 times
Machine Model (MM)	200 V Min.	EIAJ ED-4701-1 C111, 200 pF, 0 Ω, 1 time

[11] Reflow Profile (follow to IPC / JEDEC J-STD-020D.1)



[12] Packing Information TG2016SMN

- (12-1) Product number last 2 digits code(<u>xx</u>) define Quantity. The standard is "25", 12 000 pcs/Reel. X1G005441xxxx<u>xx</u>
- (12-2) Taping Specification

Subject to EIA-481 & IEC-60286

(1) Tape Dimensions TE0804L

Material of the Carrier Tape : PS Material of the Top Tape : PET+PE



TG2520SMN

(12-1) Product number last 2 digits code(<u>xx</u>) define Quantity. The standard is "27", 10 000 pcs/Reel. X1G005421xxxx<u>xx</u>



[13] Handling Precautions

Prior to using this product, please carefully read the section entitled "Precautions" on our Web site (https://www5.epsondevice.com/en/information/#precaution) for instructions on how to handle and use the product properly to ensure optimal performance of the product in your equipment.

Before using the product under any conditions other than those specified therein,

please consult with us to verify and confirm that the performance of the product will not be negatively affected by use under such conditions.

In addition to the foregoing precautions, in order to avoid the deteriorating performance of the product, we strongly recommend that you DO NOT use the product under ANY of the following conditions:

- (1) Do not expose this product to excessive mechanical shock or vi
- (2) This product can be damaged by mechanical shock during the soldering process depending on the equipment used, process conditions, and any impact forces experienced. Always follow appropriate procedures, particularly when changing the assembly process in anyway and be sure to follow applicable process qualification standards before starting production.
- (3) These devices are sensitive to ESD, please use appropriate precautions during handling, assembly, test, shipment, and installation.
- (4) This product contains semiconductor content that should not be exposed to electromagnetic waves.
- (5) The use of ultrasonic technology for cleaning, bonding, etc. can damage the Xtal unit inside this product. Please carefully check for this consideration before using ultrasonic equipment for volume production with this product.
- (6) Noise and ripple on the power supply may have undesirable affects on operation and cause degradation of phase noise characteristics. Evaluate the operation of this device with appropriate power supplies carefully before use.
- (7) When applying power, ensure that the supply voltage increases monotonically for proper operation. On power down, do not reapply power until the supplies, bypass capacitors, and any bulk capacitors are completely discharged since that may cause the unit to malfunction.
- (8) Aging specifications are estimated from environmental reliability tests and expected frequency variation over time. They do not provide a guarantee of aging over the product lifecycle.
- (9) The metal cap on top of the device is directly connected to the GND terminal (pin #2). Take necessary precautions to prevent any conductor not at ground potential from contacting the cap as that could cause a short circuit t
- (10)Do not route any signal lines, supply voltage lines, or GND lines underneath the area where the oscillators are mounted including any internal layers and on the opposite side of the PCB. To avoid any issues due to interference of other signal lines, please take care not to place signal lines near the product as this may have an adverse affect on the performance of the product.
- (11)A bypass capacitor of the recommended value(s) must be connected between the V_{CC} and GND terminals of the product. Whenever possible, mount the capacitor(s) on the same side of the PCB and as close to the product as possible to keep the routing traces short.
- (12)Power supply connections to Vcc and GND pins should be routed as thick as possible while keeping the high frequency impedance low in order to get the best performance.
- (13) The use of a filter or similar element in series with the power supply connections to protect from electromagnetic radiation noise may increase the high frequency impedance of the power supply line and may cause the oscillator to not operate properly. Please verify the design to ensure sufficient operational margin prior to use.
- (14) Keep PCB routing from the output terminal(s) to the load as short as possible for best performance.
- (15) Do not short the output to GND as that will damage the product. Always use with an appropriate load resistor connected.
- (16) Product failures during the warranty period only apply when the product is used according to the recommended operating conditions described in the specifications. Products that have been opened for analysis or damaged will not be covered. It is recommended to store and use in normal temperature and humidity environments described in the specifications to ensure frequency accuracy and prevent moisture condensation. If the product is stored for more than one year, please confirm the pin solderability prior to use.
- (17) If the oscillation circuit is exposed to condensation, the frequency may change or oscillation may stop. Do not use in any conditions where condensation occurs.
- (18) Do not store or use the product in an environment where it can be exposed to chemical substances that are corrosive to metal or plastics such as salt water, organic solvents, chemical gasses, etc. Do not use the product when it is exposed to sunlight, dust, corrosive gasses, or other materials for long periods of time.
- (19) When using water-soluble solder flux make sure to completely remove the flux residue after soldering. Pay particular attention when the residues contain active halogens which will negatively affect the product and its performance.
- (20) Do not touch the surface of the IC with tweezers or other hard tools.
- (21) Do not use adhesives with this product as this will cause the oscillation to stop if the IC is damaged by adhesive. This product uses an underfill material on the bottom side of package where adhesive near the bottom side may cause the TCXO to be damaged by thermal expansion.

PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Seiko Epson, all environmental initiatives operate under the Plan-Do-Check-Action (PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.

WORKING FOR HIGH QUALITY

In order provide high quality and reliable products and services than meet customer needs, Seiko Epson made early efforts towards obtaining ISO9000 series certification and has acquired ISO9001 for all business establishments in Japan and abroad. We have also acquired IATF 16949 certification that is requested strongly by major manufacturers as standard.

Explanation of marks used in this datasheet

Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

management that was established by the International Standards

ISO 14000 is an international standard for environmental

IATF 16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

Pb Free	●Pb free.	
	Complies with EU RoHS directive.	
RoHS	*About the products without the Pb-free mark.	
	Contains Pb in products exempted by EU RoHS directive	
	(Contains Pb in sealing glass, high melting temperature type solder or other)	

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